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Atty. Docket No.: P67358US0  
CUSTOMER NUMBER: 00136

Honorable Commissioner for Patents  
Washington, D.C. 20231

Sir:

Transmitted herewith for filing is the patent application in the name of:

Hyung-Jun KIM of Ichon-shi, Republic of Korea,

for SEMICONDUCTOR DEVICE CAPABLE OF PREVENTING CORROSION OF METAL WIRES FROM CMP (CHEMICAL MECHANICAL POLISHING) PROCESS. The application comprises a 13-page specification including 11 claims (2 independent) and Abstract, 3 sheets of drawings (Figs. 1-4), and a Declaration and Power of Attorney.

Also accompanying this application for filing are:

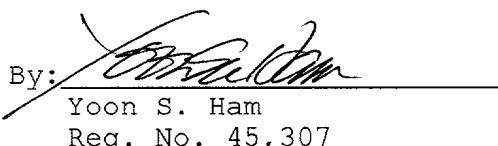
- (1) Assignment document, cover sheet and \$40.00 fee for recordation of Assignment; and
- (2) A certified copy of Korean Application No. 2000-80891, filed December 22, 2000, the priority of which is claimed under 35 U.S.C. §119.

The filing fee has been calculated as shown:

Large Entity	\$ 740.00
Total Claims=11; in excess of 20 = 0 x (\$18.00) =	
Total Ind. Claims=02; in excess of 03 = 3 x (\$84.00) = +	
TOTAL FILING FEE:	\$ 740.00

A check in the amount of \$780.00, is enclosed to cover the Filing Fee and an Assignment Recordation Fee. The Commissioner is hereby authorized to charge payment of any fees set forth in Sections 1.16 or 1.17 during the pendency of this application, or credit any overpayment, to deposit Account No. 06-1358. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

By:   
Yoon S. Ham  
Reg. No. 45,307

Enclosures  
YSH:ecl